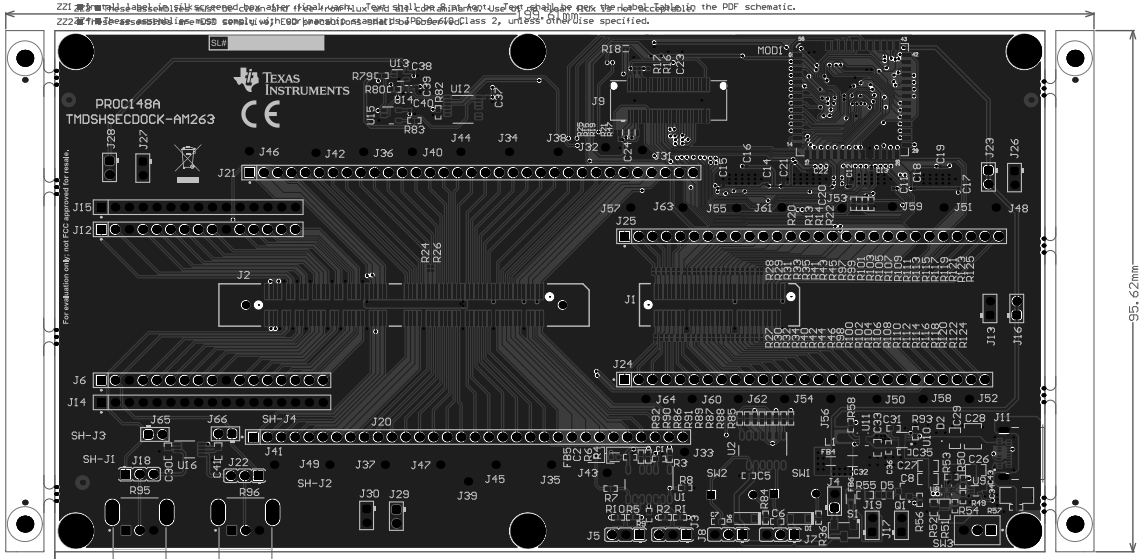
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.00mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 2	FR-4	3.70mil	4.1	
2	GND01		1.38mil		
	Dielectric 1	FR-4	48.00mil	4.8	
3	PWR/GND02		1.38mil		
	Dielectric 3	FR-4	3.70mil	4.1	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	1.00mil	3.5	
	Bottom Overlay				

IMPEDENCE TABLE :

LAYER	TRACE WIDTH	SPACING	IMPEDANCE +/- 10%	REFERENCE LAYER
TOP	4 MILS	5 MILS	120OHM	LAYER-3
TOP/BOT	4 MILS	-	50 OHM	LAYER-2 /LAYER-3



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED

.VariantName

DESIGN INFORMATION	
MIN. TRACK WIDTH:	4 MIL
MIN. CLEARANCE:	4 MIL
MIN. VIA PAD SIZE:	18 MIL
MINIMUM ANNULAR RING 0.12mm (5MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL	

MATERIAL:
- [ ] FR-408 [X] FR-4 High Tg [ ] OTHER
- THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
- TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
- BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
- REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
- PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
- SILKSCREEN: [X] TOP [X] BOTTOM
- SILKSCREEN COLOR: [X] WHITE [ ] OTHER
- SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
- [ ] MATTE [X] SEMI-GLOSS
- SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
- [ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
- ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
- [ ] N.C. ROUTE [X] Breakaway Tabs
- CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
- [X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
- [X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
- MICROSECTION: [ ] YES
- BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
- [X] 8MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
- [ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
- [ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
- [ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE:	.PRJ_Title
DESIGNED FOR:	.PRJ_Customer
FILE NAME:	PROC148A.PcbDoc

ALL ARTWORK VIEWED FROM TOP, SOLDER SIDE

LAYER NAME = M1 Board Outline

PLOT NAME = Composite

TID #: .TIDOIT.

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ENGINEER: .PRJ_Engineer	LAYOUT BY: .PCB_Layout
SCALE: 1.00	ALTIUM DESIGNER VERSION: 22.8.2.66